

Sumikon® EME-7710

Epoxy; Epoxide
Sumitomo Bakelite Co., Ltd.

Message:

Sumikon 7700-Series compounds are multi-functional-type molding compounds developed for overmolded BGA packages.

General Information			
UL YellowCard	E41429-232559		
Uses	Semiconductor molding compound		
Forms	Liquid		
Processing Method	Enclosure		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.89	g/cm ³	ASTM D792
Water Absorption (24 hr)	0.40	%	ASTM D570
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus (25°C)	11300	MPa	ASTM D790
Flexural Strength (25°C)	93.2	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	190	°C	ASTM E1356
Thermal Conductivity	0.75	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+13	ohms·cm	ASTM D257
Thermoset	Nominal Value	Unit	
Demold Time (175°C)	1.5 - 2.0	min	
Post Cure Time (175°C)	2.0 - 8.0	hr	

Additional Information

Spiral Flow, SB-U-03-003: 75 cmGel Time, SB-U-03-005, 175°C: 32 secThermal Expansion, SB-U-02-002, TTg: 5.5 E-5/°CFlexural Strength, SB-U-01-001, 240°C: 20.6 MPaFlexural Modulus, SB-U-01-002, 240°C: 1373 MPaUL-94 Flame Class, SB-U-03-003: V-0Extracted Na+, SB-U-04-043: <1 ppmExtracted Cl-, SB-U-04-043: 5 ppmTransfer Pressure: 687-1177 MPa

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Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 1342475533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China



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